

## PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Takehiro Fujii

Examiner: Unassigned

Serial No.: Unassigned

Group Art Unit: Unassigned

Filed: Herewith

Docket: 362-59 PCT/US

For: SIDE-EMISSION TYPE  
SEMICONDUCTOR LIGHT-EMITTING  
DEVICE AND MANUFACTURING METHOD  
THEREOF

Dated: 21 December 2001

Commissioner for Patents  
Washington, DC 20231

Customer No.: 23869

PRELIMINARY AMENDMENT

Sir:

Prior to the examination of this application, please amend the application as follows:

IN THE CLAIMS:

Please amend claims 7 and 13 by rewriting the same as follows:

91

7. (Amended) A side-emission type semiconductor light-emitting device according to claim 4, wherein said LED chip has a bonding wire extending from a top surface, and said concave portion is formed directly above said LED chip.

92

13. (Amended) A side-emission type semiconductor light-emitting device according to claim 11, wherein a center of said application area is deviated from a center of said substrate to said opposite direction.

Please add the following new claims: